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5,772,905, issued June 30, 1998 from application Serial No. 08/558,809 filed November 15, 1995.--

IN THE CLAIMS

Amend claim 1 to read as follows:

1. In a lithographic method for forming a pattern in a film carried on a substrate, comprising the steps of:

providing a mold having a protruding feature and a recess formed thereby, the feature and the recess having a shape forming a mold pattern;

depositing a film on a substrate;

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urging the mold into the film whereby the thickness of the film under the protruding feature is reduced and a thin region is formed in the film;

removing the mold from the film;

processing the relief whereby the thin region is removed exposing a portion of the surface of the substrate which underlies the thin region; and

whereby the exposed portion of the surface of the substrate substantially replicates the mold pattern,

the improvement wherein at least a portion of said protruding feature and a portion of said recess have bonded thereto a release material comprising an inorganic linking group bonded to a molecular chain having release properties.